

To: Commissioner for Patents
P.O.Box 1450
Alexandria, VA 22313-1450

Subject: | Serial No. 10/724,784 12/01/03 |

May-Ho Ko

FLASH PROCESS FOR STACKING POLY
ETCHING

Enclosed is Form PTO-1449, Information Disclosure Citation
In An Application.

CERTIFICATE OF MAILING

Stephen B. Ackerman, Reg.# 37761

Signature/Date SPB AD 2/23/04

U.S. Patent 6,165,375 to Yang et al., "Plasma Etching Method," discloses a flash step in an etch process.

U.S. Patent 6,165,861 to Liu et al., "Integrated Circuit Polysilicon Resistor Having a Silicide Extension to Achieve 100% Metal Shielding from Hydrogen Intrusion," discloses a method for a mixed mode product.

The following two U.S. Patents discloses processes for mixed mode products using poly etches:

- 1) U.S. Patent 6,103,622 to Huang, "Silicide Process for Mixed Mode Product with Dual Layer Capacitor and Polysilicon Resistor which is Protected with a Capacitor Protective Oxide During Silicidation of FET Device."
- 2) U.S. Patent 6,103,621 to Huang, "Silicide Process for Mixed Mode Product with Dual Layer Capacitor which is Protected by a Capacitor Protective Oxide During Silicidation of FET Device."

Sincerely,



Stephen B. Ackerman,
Reg. No. 37761

Form PTO-1449

INFORMATION DISCLOSURE CITATION
IN AN APPLICATION

(Use several sheets if necessary)

Docket Number (Optional)

TSMC-00-932

Application Number

10/724,784

Applicant

May-Ho Ko

Filing Date

12/01/03

Group Art Unit

U. S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILED DATE IF APPROPRIATE
	6165375	12/26/00	Yang et al.	216	67	9/23/97
	6165861	12/26/00	Liu et al.	438	382	9/14/98
	6103622	8/15/00	Huang	438	652	3/29/99
	6103621	8/15/00	Huang	438	652	3/29/99

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						YES	NO

OTHER DOCUMENTS (Including Author, Title, Date, Portraits Pages, Etc.)

EXAMINER

DATE CONSIDERED

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.

